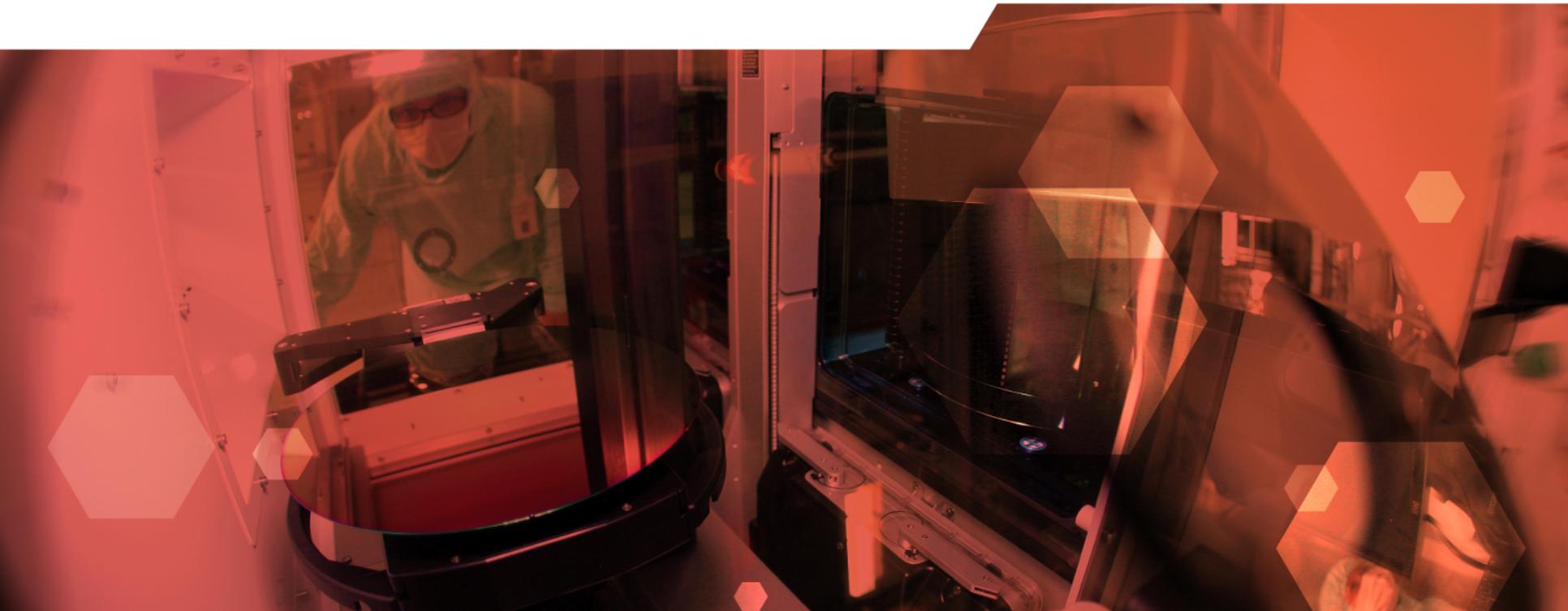


North America TC Chapter Traceability Global Technical Committee

Liaison Report

November 2018

v1



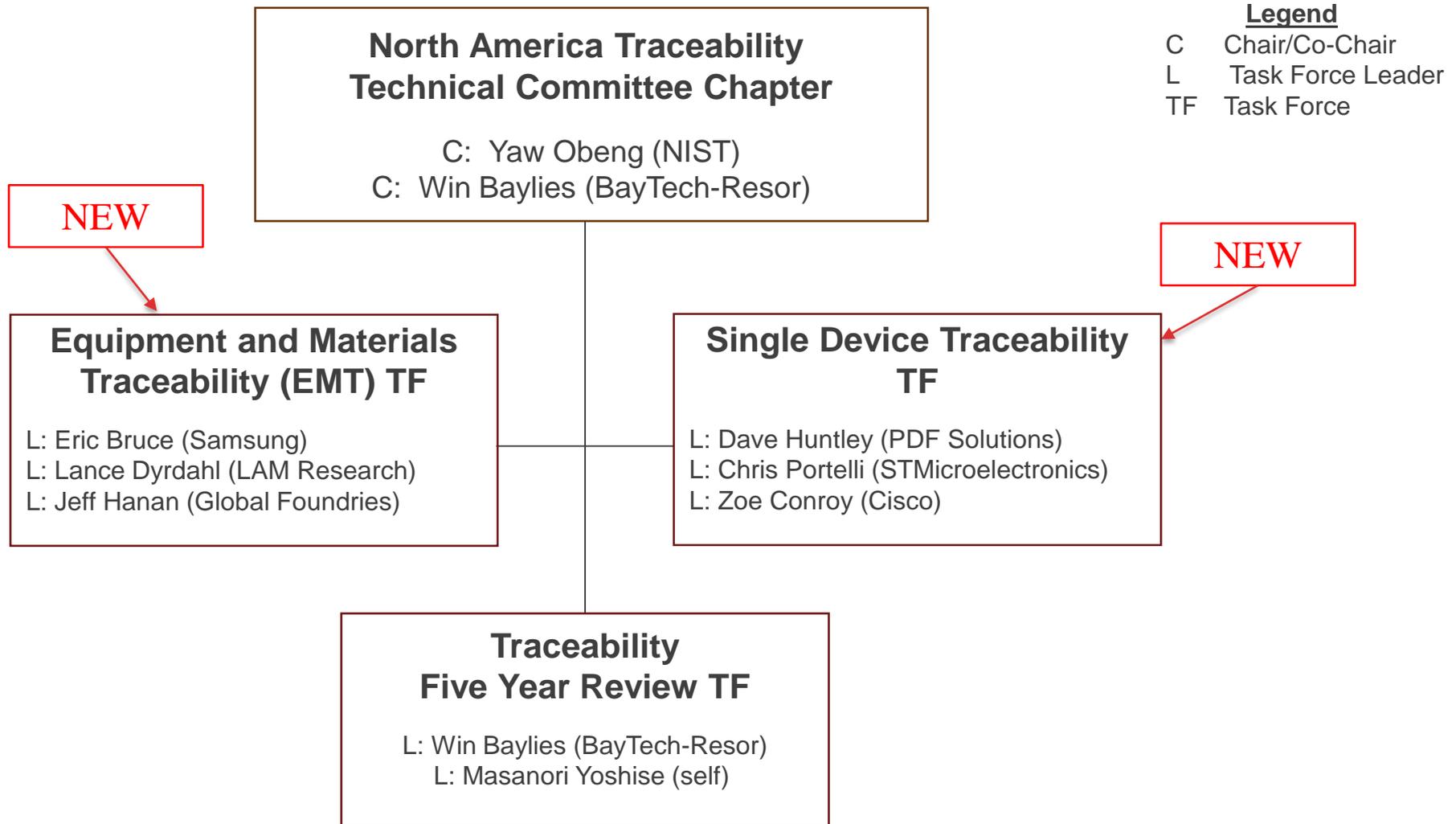
Outline

- Leadership
- Organization Chart
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Leadership

- N.A. Traceability TC Chapter Cochairs (no change)
 - Yaw Obeng / NIST
 - Win Baylies / BayTech-Resor
- Leadership Changes
 - None

N.A. Traceability TC Chapter Organization



Meeting Information

- Last meeting
 - November 8, 2018 at Fall 2018 Standards Meetings
 - SEMI HQ, Milpitas, CA
- Next meeting
 - April 4, 2019 at Spring 2019 Standards Meetings
 - SEMI HQ, Milpitas, CA

Ballot Results Cycle 7-2018

Document #	Document Title	Committee Action
6428	Reapproval to SEMI T3-1213, <i>Specification for Wafer Box Labels</i>	passed
6429	Reapproval to SEMI T4-0301 (Reapproved 1213), <i>Specification for 150 mm and 200 mm Pod Identification Dimensions</i>	passed
6450	New Standard – <i>Specification for Single Device Traceability for the Supply Chain</i>	passed with editorial changes

Activities Approved via GCS between Meetings

#	Type	SC/TF/WG	Details
6448	SNARF	EMT TF	New Standard – <i>Specification for Equipment and Materials Label</i>
6449	SNARF	EMT TF	New Standard – <i>Specification for Equipment and Materials Part Traceability</i>
6450	SNARF	SDT TF	New Standard – <i>Specification for Single Device Traceability for the Supply Chain</i>

Authorized Activities

#	Type	SC/TF/WG	Details
6471	SNARF	SDT TF	Line Item Revision to New Standard (designation TBD)– <i>Specification for Single Device Traceability for the Supply Chain</i> New SNARF approved at TC meeting

Open SNARFs

- 6438, Reapproval to SEMI T3-1213, *Specification for Wafer Box Labels*
- 6429, Reapproval to SEMI T4-0301 (Reapproved 1213), *Specification for 150 mm and 200 mm Pod Identification Dimensions*
- 6448, New Standard – Specification for Equipment and Materials Label
- 6449, New Standard – *Specification for Equipment and Materials Part Traceability*
- 6450, New Standard – *Specification for Single Device Traceability for the Supply Chain*
- 6471, Line Item Revision to New Standard (designation TBD)– *Specification for Single Device Traceability for the Supply Chain*

5 Year Review Traceability

Designation	Standard Title	Action By	Assigned to
SEMI T11-0703 (Reapproved 1014)	Specification for Marking of Hard Surface Reticle Substrates	10/30/2019	TBD

Task Force Highlights

Equipment and Materials Traceability (EMT) Task Force Report

- Leadership Change / Ballot Adjudication / New SNARF(s)
 - None
- Upcoming ballots (Spring 2019 Meetings)
 - 6448 - New Standard: *Specification for Equipment and Materials Part Labels*
 - 6449 - New Standard : *Specification for Equipment and Materials Part Traceability*
- Ongoing work on draft Ballots – focusing on #6428 first
 - Look at IDM requirements as a starting point
 - What needs to be supported for ‘grandfathered’ requirements.
 - What needs to be handled forward looking
 - Looking for other IDM input (Specifically someone at Intel - they have lots of existing standards related to topic – example RossettaNet)
Would like to make sure their requirements are incorporated.
 - Looking for contacts who etches parts to understand best practices.
(2D identifications)
- Educational Workshop- will present EMT TF purpose and ballot proposals along with SDT TF at SEMICON Japan 2018

Single Device Traceability Task Force Update

- Leadership Change
 - None
- Ballot Adjudication (**passed with editorial changes**)
 - 6450, New Standard: *Specification for Single Device Traceability for the Supply Chain*
- New SNARF(s)
 - Line Item Revision to New Standard (designation TBD)– *Specification for Single Device Traceability for the Supply Chain*
 - To incorporate technical feedback received during balloting doc #6450
- Upcoming work - proposal for new anticounterfeiting Standard
 - SNARF authorization planned for Spring 2019 Standards Meetings or earlier via GCS
 - To evaluate T21 as related to new proposed standard for anticounterfeiting
- Educational Workshop - will present SDT TF purpose and ballot proposals along with EMT TF at SEMICON Japan 2018

Traceability Five Year Review Force Update

- Leadership Change
 - None
- Ballot Adjudication (**passed**)
 - 6428, Reapproval to SEMI T3-1213, Specification for Wafer Box Labels
 - 6429, Reapproval to SEMI T4-0301 (Reapproved 1213), *Specification for 150 mm and 200 mm Pod Identification Dimensions*
- New SNARF(s)
 - None
- Other activities
 - Review SEMI T11-0703, *Specification for Marking of Hard Surface Reticle Substrates*
 - Review at SEMICON West 2019

Next N.A. Traceability Meeting Schedule

The next N.A. Traceability TC Chapter Meeting is tentatively scheduled* for Thursday, April 4 2019 at the SEMI HQ in Milpitas, California in conjunction with Spring Standards 2019 meetings.

Thursday, April 4, 2018

- 5 Year Review TF (11:30AM – 12:30PM) <tentative>
- Equipment and Materials Traceability TF (12:30PM – 2:00PM)
- Single Device Traceability TF (2:00PM – 3:30PM)
- Traceability TC Chapter (3:30PM – 5:00PM)

*All times are in Pacific Standard Time. Times and dates are subject to change without notice. For meeting details, registration, the latest schedule, and travel information please visit <http://www.semi.org/en/standards-events>.

Thank you!

For more information or to participate in any N.A. Traceability activities, please contact Inna Skvortsova at SEMI
(iskvortsova@semi.org)